

**CLAIMS**

1. A film carrier tape for mounting electronic devices thereon which comprises an insulating film and a wiring pattern formed thereon at least a part of which is plated with a tin-bismuth alloy,

wherein bismuth content in the tin-bismuth alloy deposit formed by plating is substantially uniform along a thickness direction thereof.

2. The film carrier tape for mounting electronic devices thereon according to claim 1, wherein said tin-bismuth alloy deposit is formed on a tin deposit formed on said wiring pattern by plating.

3. A production method of a film carrier tape for mounting electronic devices thereon which comprises:

plating at least a part of a wiring pattern formed on an insulating film with a tin-bismuth alloy; and

washing a portion plated with the tin-bismuth alloy within 6 seconds after the plating is completed.

4. The production method according to claim 3, wherein the plating is conducted by contacting at least a part

of the film carrier tape with a plating solution for forming a tin-bismuth alloy deposit.

5. A plating apparatus for a film carrier tape for mounting electronic devices thereon, said plating apparatus comprising a plating tank, a slit inlet opening through which the film carrier tape successively enters the plating tank, a slit outlet opening through which the film carrier tape exits the plating tank, and a washing nozzle for washing the film carrier tape which has exited the plating tank through the slit outlet opening.

6. The plating apparatus according to claim 5, wherein said washing nozzle is positioned between said plating tank and a washing tank provided for washing the film carrier tape.

7. The plating apparatus according to claim 5, which includes at least two washing nozzles provided in connection with a flexible tube.